



1FW

PATENT
Docket No. 20059/PIA31205

**IN THE UNITED STATES PATENT
AND TRADEMARK OFFICE**

Applicant(s):

OH, Sang Jun

U.S. Serial No.: 10/764,905

For: "Methods for Forming an Air
Gap in a Semiconductor Metal Line
Manufacturing Process"

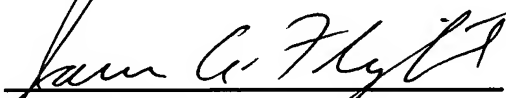
Filed: January 26, 2004

Group Art Unit: 1756

Examiner: Not yet Assigned

) I hereby certify that this paper and the
) documents referred to as enclosed
) therewith are being deposited with the
) United States Postal Service as first
) class mail, postage prepaid, in an
) envelope addressed to Commissioner
) for Patents, P.O. Box 1450,
) Alexandria, Virginia 22313-1450 on
) this date:

June 8, 2005

) 
) James A. Flight
) Attorney for Applicant(s)
) Registration No. 37,622

STATUS LETTER

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

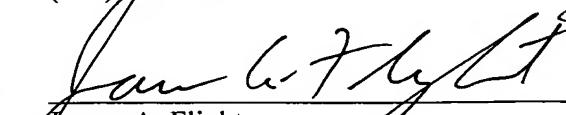
Kindly advise when an Office action can be expected in the above-referenced
matter.

Respectfully submitted,

HANLEY, FLIGHT & ZIMMERMAN, LLC
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June 8, 2005

By:


James A. Flight
Registration No.: 37,622